# Monthly LabAdviser update: 3/7 2018

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| Updated Subject  | Contributor | Link to the updated pages |
| **Aligner Maskless 01**Section “Exposure technology” has been added.Updated: “Writing speed” and “Resolution” in the section: “Process Parameters” | **Thomas A. Anhøj @danchip** | [http://labadviser.danchip.dtu.dk/index.php/Specific\_Process\_Knowledge/Lithography/Aligners/Aligner:\_Maskless\_01\_processing](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/Aligners/Aligner%3A_Maskless_01_processing) |
| **PECVD4**Uniformity of LF\_SiO2 deposition on 7x2” carrierUniformity of MF\_SiN on PECVD4. 7 2” wafers on the 7x2” carrier | **Jesper F. Hansen @NILT** | [Deposition of Silicon Oxide using PECVD/LF SiO2 results](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide/Deposition_of_Silicon_Oxide_using_PECVD/LF_SiO2_results)[Deposition of Silicon Nitride using PECVD/MF SiN results](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Nitride/Deposition_of_Silicon_Nitride_using_PECVD/MF_SiN_results) |
| **ASE**New page on SiO2 etching in the ASE | **Berit G. Herstrøm @danchip** | [Etch/Etching\_of\_Silicon\_Oxide/SiO2\_etch\_using\_ASE](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon_Oxide/SiO2_etch_using_ASE) |
| **III-V ICP**Adding new results on InP etching. Conclusion so fare: use SiO2 carrier – not Si. Or you will get bottom roughness in the open areas | **Karen Birkelund and Berit G. Herstrøm @danchip** | [III-V\_ICP/InP-InGaAsP-InGaAs#InP\_etching\_June\_2018](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/III-V_ICP/InP-InGaAsP-InGaAs#InP_etching_June_2018) |
| **DRIE Pegasus**DRIE Pegasus page updated with Pegasus 2Comparison of DRIE trench profiles | **Jonas Michael-Lindhard** | [Etch/DRIE-Pegasus](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus)[DRIE-Pegasus/TrenchCharacterisation](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/TrenchCharacterisation) |

# Equipment Manuals updated in LabManager:

As an approved user on a piece of equipment you have to make sure you have read and understood the latest version of the manual before using the equipment.

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| **5. 3. 7.53) Manual for XRD SmartLab**, ver 1 |
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| **5. 3. 7.11) Manual for Nikon ECLIPSE L200 optical microscope**, ver 5 |
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| **5. 3. 3.12) Manual for IBE/IBSD Ionfab 300**, ver 1.7 |
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| **5. 3. 5.02) Manual for Phosphorus Drive-in furnace (A3)**, ver 8 |
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| **5. 3. 2.05) Manual for LPCVD nitride furnace (6") E3**, ver 7 |
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| **5. 3. 2.04) Manual for LPCVD Nitride Furnace (4")**, ver 7 |
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| **5. 3. 3.17) Manual for Si Etch 3: KOH**, ver 2 |
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| **5. 3. 5.16) Manual for Furnace: Multipurpose Annealing**, ver 2.3 |
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| **5. 3. 2.03) Manual for Wordentec**, ver 10 |
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| **5. 3. 2.26) Manual for Temescal E-beam Evaporator**, ver 1 |
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| **5. 3. 8.06) Manual for Developer: E-beam**, ver 1.2 |
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